

Low drop power Schottky rectifier

Features

- Very small conduction losses
- Negligible switching losses
- Low forward voltage drop
- Surface mount miniature packages
- Avalanche capability specified

Description

Single chip Schottky rectifiers suited to switched mode power supplies and high frequency DC to DC converters.

Packaged in SMA, SMB and STmite flat this device is especially intended for surface mounting and used in low voltage, high frequency inverters, free wheeling and polarity protection applications.

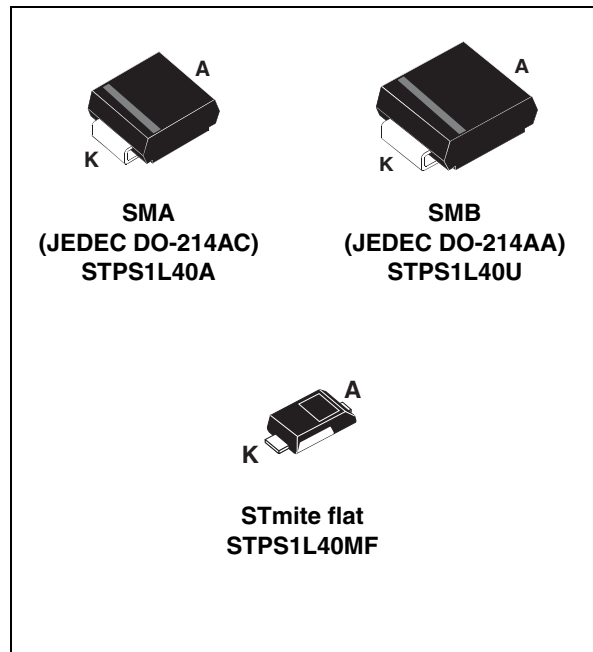


Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	1 A
V_{RRM}	40 V
T_j (max)	150 °C
V_F (max)	0.42 V

1 Characteristics

Table 2. Absolute ratings (limiting values)

Symbol	Parameter		Value	Unit
V _{RRM}	Repetitive peak reverse voltage		40	V
I _{F(RMS)}	Forward rms current	SMA / SMB	8	A
		STmite flat	2	
I _{F(AV)}	Average forward current	SMA / SMB	1	A
		STmite flat		
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal	60	A
I _{RRM}	Repetitive peak reverse current	t _p = 2 μs F = 1 kHz square	1	A
I _{RSM}	Non repetitive peak reverse current	t _p = 100 μs square	1	A
P _{ARM}	Repetitive peak avalanche power	t _p = 1 μs T _j = 25 °C	900	W
T _{stg}	Storage temperature range		- 65 to + 150	°C
T _j	Maximum operating junction temperature ⁽¹⁾		150	°C
dV/dt	Critical rate of rise of reverse voltage		10000	V/μs

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter		Value	Unit
R _{th(j-l)}	Junction to lead	SMA	30	°C/W
		SMB	25	
R _{th(j-c)}	Junction to case	STmite flat	20	

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}	-	-	35	μA
		T _j = 125 °C		-	6	10	mA
V _F ⁽¹⁾	Forward voltage drop	T _j = 25 °C	I _F = 1 A	-	-	0.5	V
		T _j = 125 °C		-	0.37	0.42	
		T _j = 25 °C	I _F = 2 A	-	-	0.63	
		T _j = 125 °C		-	0.5	0.61	

1. Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 0.23 \times I_{F(AV)} + 0.19 I_{F(RMS)}^2$$

Figure 1. Average forward power dissipation versus average forward current

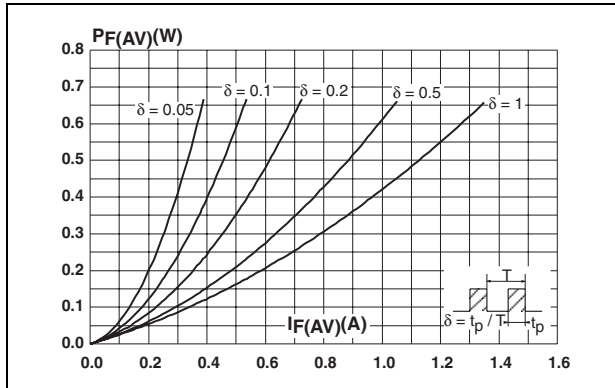


Figure 2. Average forward current versus ambient temperature (SMA, $\delta = 0.5$)

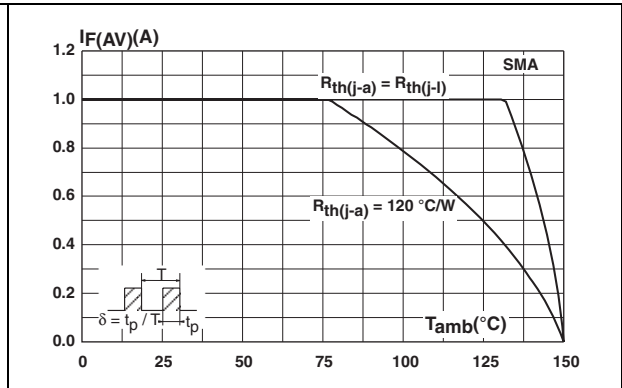


Figure 3. Average forward current versus ambient temperature (SMB, $\delta = 0.5$)

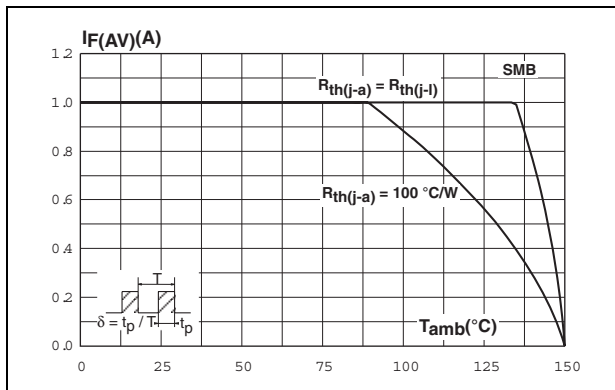


Figure 4. Average forward current versus ambient temperature (STmite flat, $\delta = 0.5$)

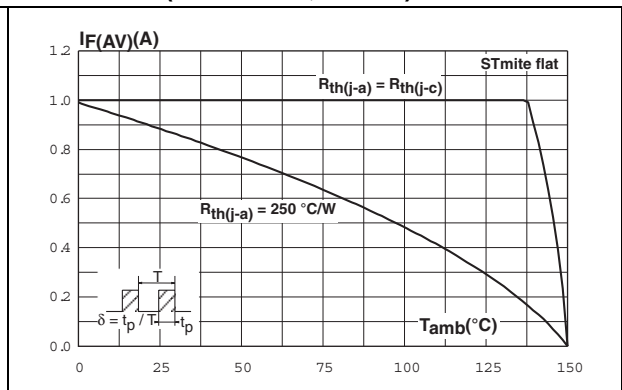


Figure 5. Normalized avalanche power derating versus pulse duration

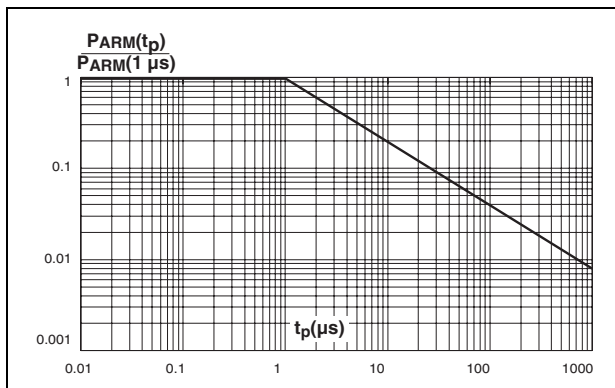


Figure 6. Normalized avalanche power derating versus junction temperature

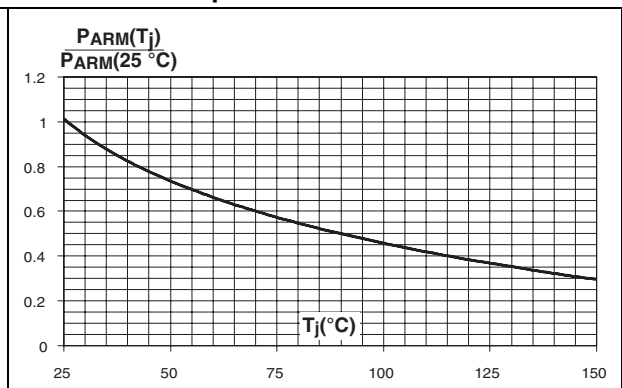


Figure 7. Non repetitive surge peak forward current versus overload duration (maximum values, SMA)

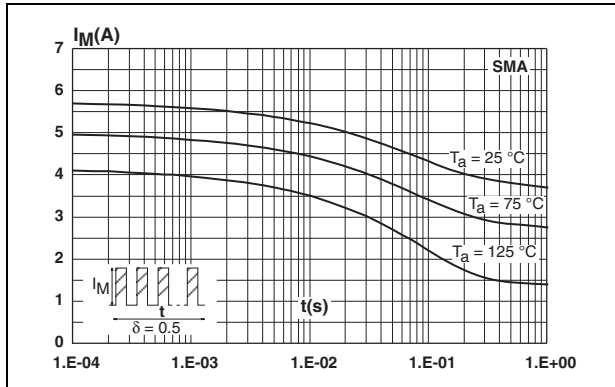


Figure 8. Non repetitive surge peak forward current versus overload duration (maximum values, SMB)

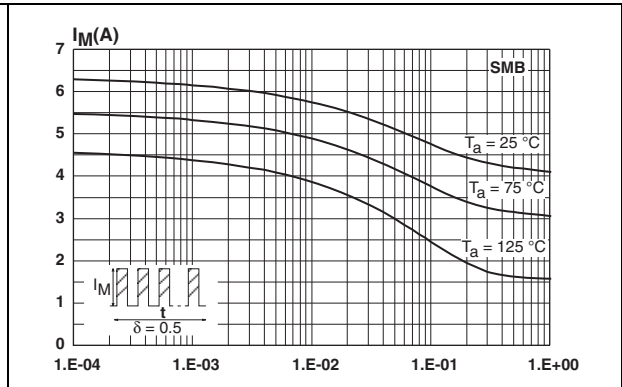


Figure 9. Non repetitive surge peak forward current versus overload duration (maximum values, STmite flat)

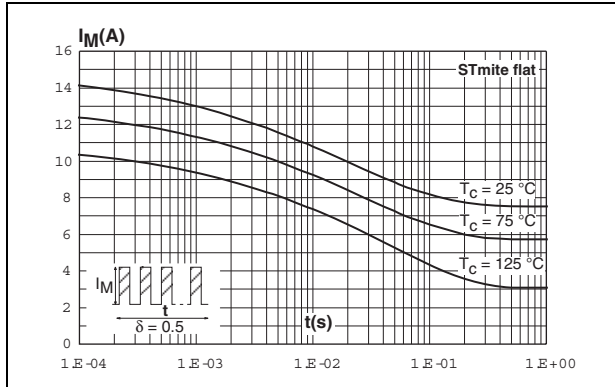


Figure 10. Relative variation of thermal impedance junction to ambient versus pulse duration (SMA)

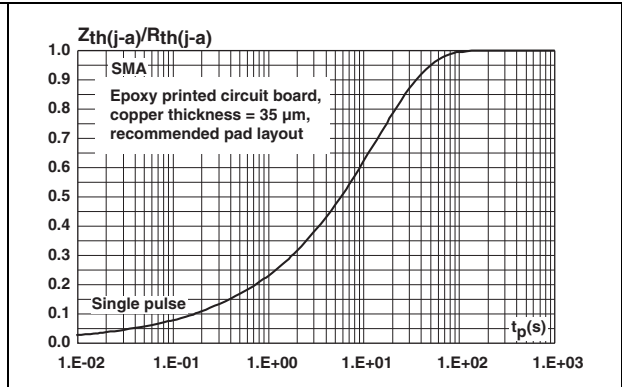


Figure 11. Relative variation of thermal impedance junction to ambient versus pulse duration (SMB)

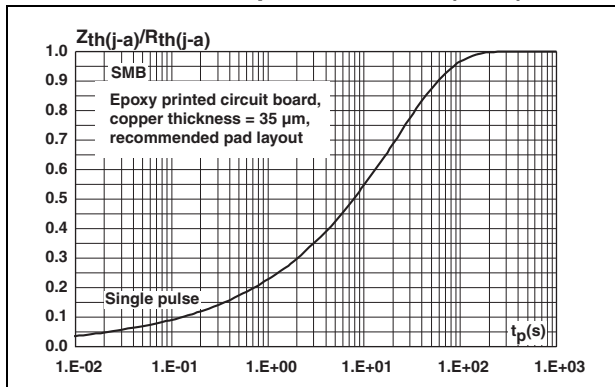


Figure 12. Relative variation of thermal impedance junction to ambient versus pulse duration (STmite flat)

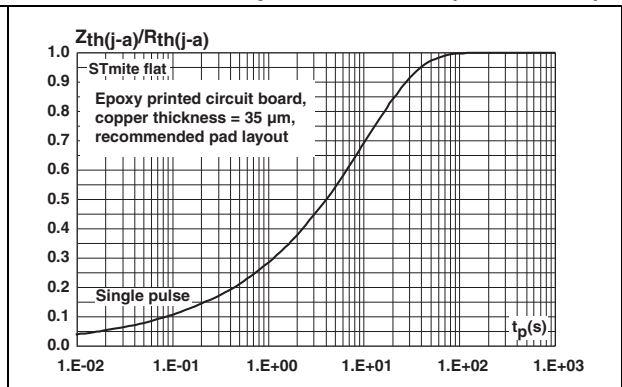


Figure 13. Reverse leakage current versus reverse voltage applied (typical values)

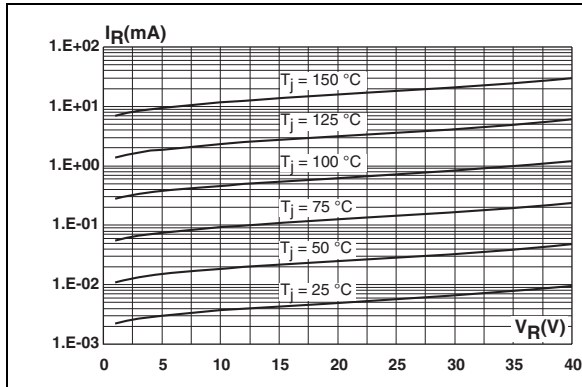


Figure 14. Junction capacitance versus reverse voltage applied (typical values)

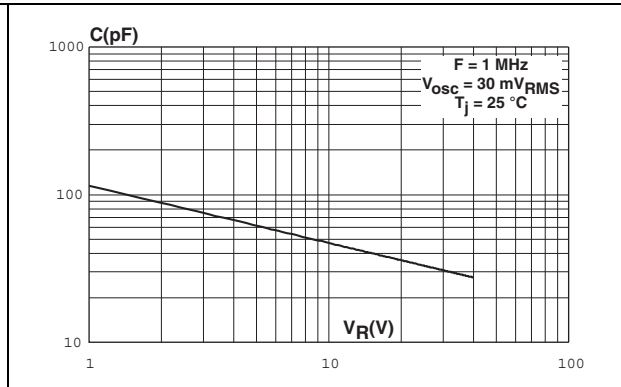


Figure 15. Forward voltage drop versus forward current (typical values, high level)

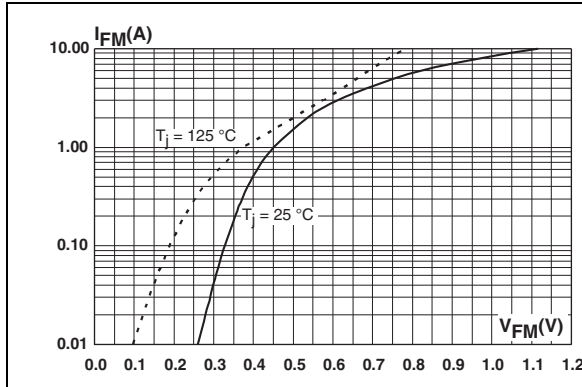


Figure 16. Forward voltage drop versus forward current (typical values, low level)

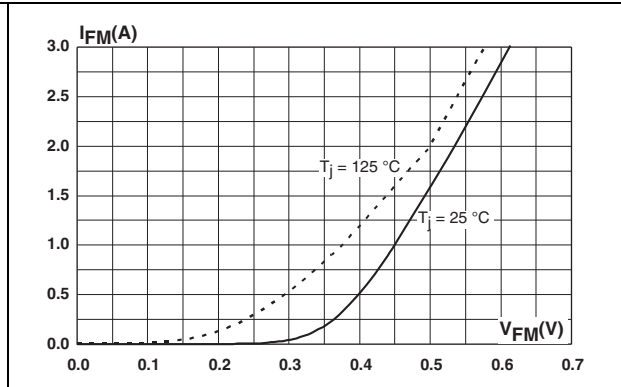


Figure 17. Thermal resistance junction to ambient versus copper surface under each lead (SMA)

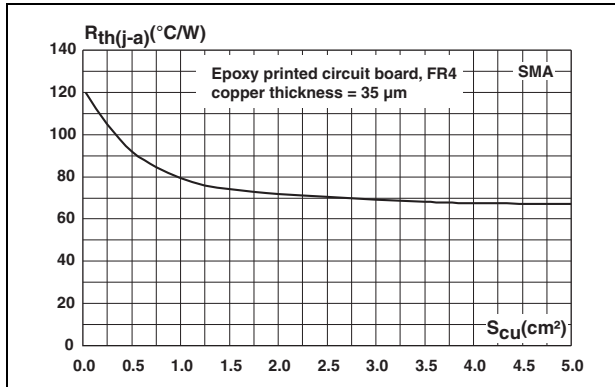


Figure 18. Thermal resistance junction to ambient versus copper surface under each lead (SMB)

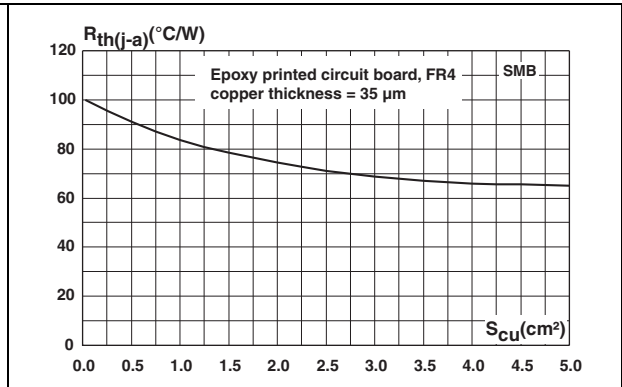
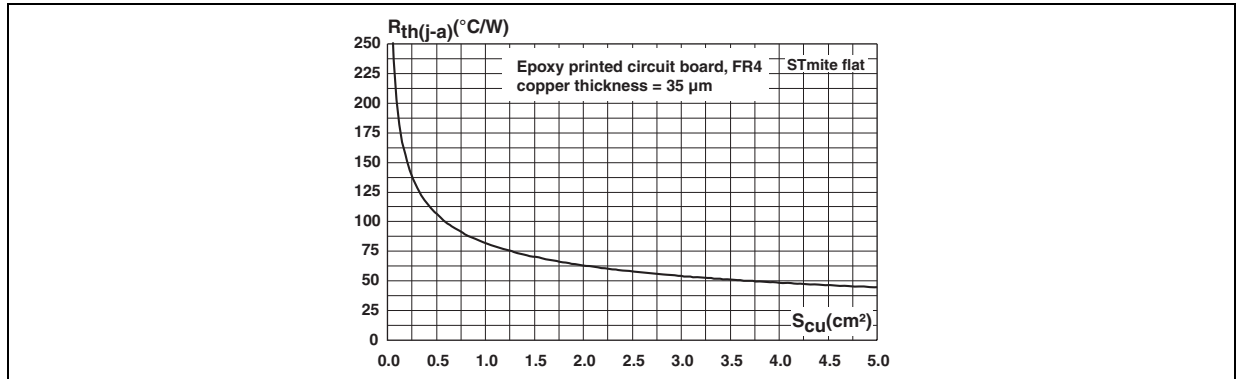


Figure 19. Thermal resistance junction to ambient versus copper surface under tab (STmite flat)



2 Package information

- Epoxy meets UL94, V0
- Cathode band (SMA, SMB)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 5. SMA dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.094
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.40	0.006	0.016
D	2.25	2.90	0.089	0.114
E	4.80	5.35	0.189	0.211
E1	3.95	4.60	0.156	0.181
L	0.75	1.50	0.030	0.059

Figure 20. Footprint, dimensions in mm (inches)

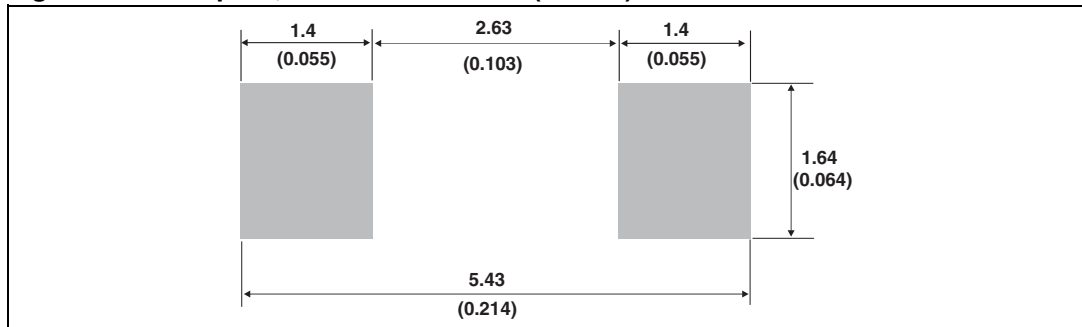


Table 6. SMB dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
D	3.30	3.95	0.130	0.156
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
L	0.75	1.50	0.030	0.059

Figure 21. Footprint, dimensions in mm (inches)

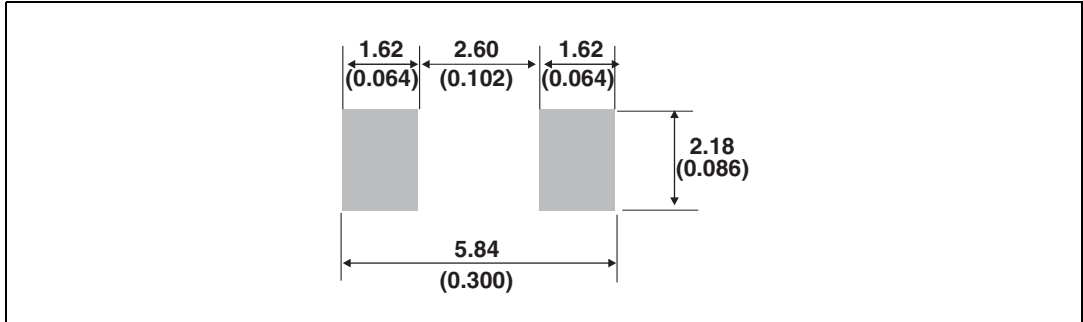
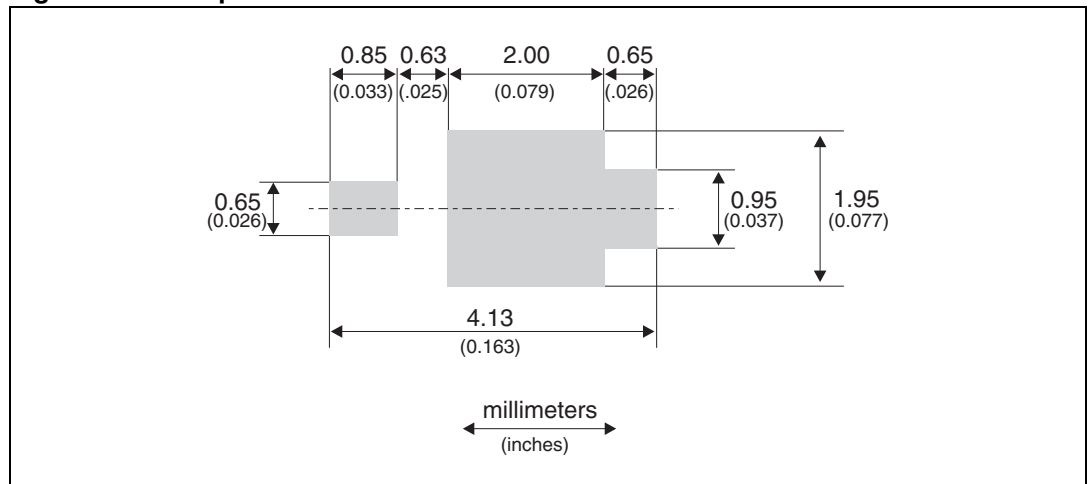


Table 7. STmite flat dimensions

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.80	0.85	0.95	0.031	0.033	0.037
b	0.40	0.55	0.65	0.016	0.022	0.026
b2	0.70	0.85	1.00	0.027	0.033	0.039
c	0.10	0.15	0.25	0.004	0.006	0.009
D	1.75	1.90	2.05	0.069	0.075	0.081
E	3.60	3.80	3.90	0.142	0.150	0.154
E1	2.80	2.95	3.10	0.110	0.116	0.122
L	0.50	0.55	0.80	0.020	0.022	0.031
L1	2.10	2.40	2.60	0.083	0.094	0.102
L2	0.45	0.60	0.75	0.018	0.024	0.030
L3	0.20	0.35	0.50	0.008	0.014	0.020

Figure 22. Footprint dimensions



3 Ordering information

Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS1L40A	GB4	SMA	0.068 g	5000	Tape and reel
STPS1L40U	GC4	SMB	0.107 g	2500	Tape and reel
STPS1L40MF	F1L4	STmite flat	0.016 g	1200	Tape and reel

4 Revision history

Table 9. Document revision history

Date	Revision	Changes
Jul-2003	4A	Last update.
Aug-2004	5	SMA package dimensions update. Reference A1 max. changed from 2.70 mm (0.106 inch.) to 2.03 mm (0.080).
24-Jun-2009	6	Added STmite flat package.

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